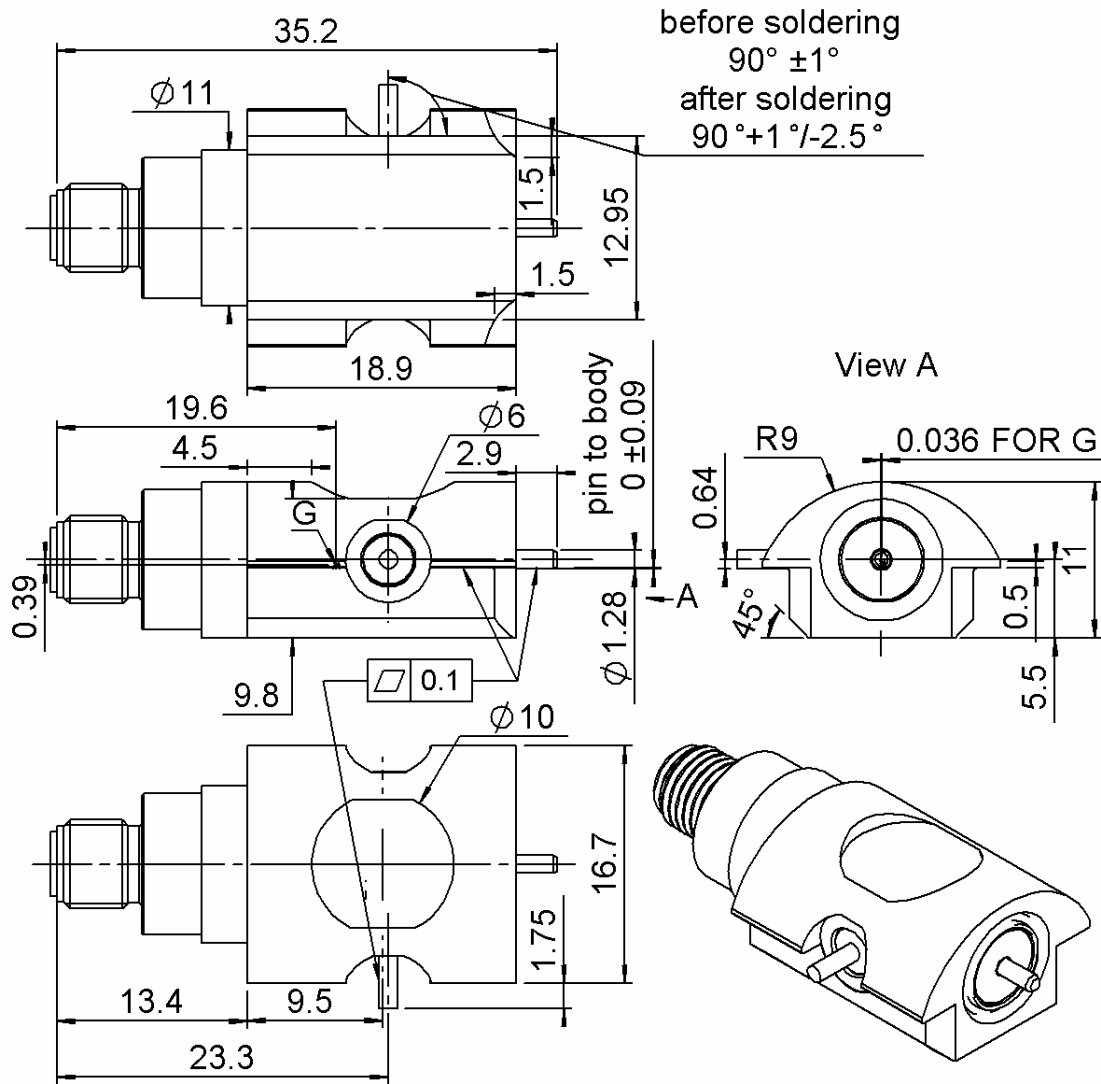


SMA SWITCH EDGE CARD SMT RIGHT TYPE

R124.422.001

PACKAGING IN REEL 110

Series : SMA-COM



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	NPGR, BBR 2
CENTER CONTACT	BERYLIUM COPPER	NPGR
OUTER CONTACT	BRASS	BBR 2
INSULATOR	PEEK	
GASKET		
OTHERS PARTS	BRASS	NPGR
-	-	-
-	-	-

Issue : 1030 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



SMA SWITCH EDGE CARD SMT RIGHT TYPE**R124.422.001****PACKAGING IN REEL 110**Series : **SMA-COM****PACKAGING**

Standard	Unit	Other
110	'W' option	Contact us

SPECIFICATION**ELECTRICAL CHARACTERISTICS**

Impedance	50	Ω
Frequency	DC-3	GHz
VSWR	1.1 + 0.1000	x F(GHz) Maxi
Isolation at DC to 1 GHz	-47	dB Typical
Isolation at 1 to 2 GHz	-43	dB Typical
Isolation at 2 to 3 GHz	-40	dB Typical
Insertion loss at DC to 1 GHz	0.1	dB Maxi
Insertion loss at 1 to 2 GHz	0.15	dB Maxi
Insertion loss at 2 to 3 GHz	0.2	dB Maxi
RF leakage	- (NA - F(GHz))	dB Maxi
Voltage rating	300	Veff Maxi
Dielectric withstanding voltage	500	Veff mini
Insulation resistance	5000	M Ω mini
Power withstanding	80	W at 0.9 GHz
	50	W at 1.8 GHz

ENVIRONMENTAL

Operating temperature	-40/+85	$^{\circ}$ C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHER CHARACTERISTICS

Assembly instruction	NA
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Others :
 Action Mating force
 20N MAX
 15N min

(1) Do not apply force on the center contact before mounting the switch on PCB

MECHANICAL CHARACTERISTICS

Center contact retention	
Axial force – Mating end	NA N mini
Axial force – Opposite end	NA N mini
Torque	NA N.cm mini
Axial force side pin	(1)
Recommended torque	
Mating	NA N.cm
Panel nut	NA N.cm
Mating life	100 Cycles mini
Weight	22.0700 g

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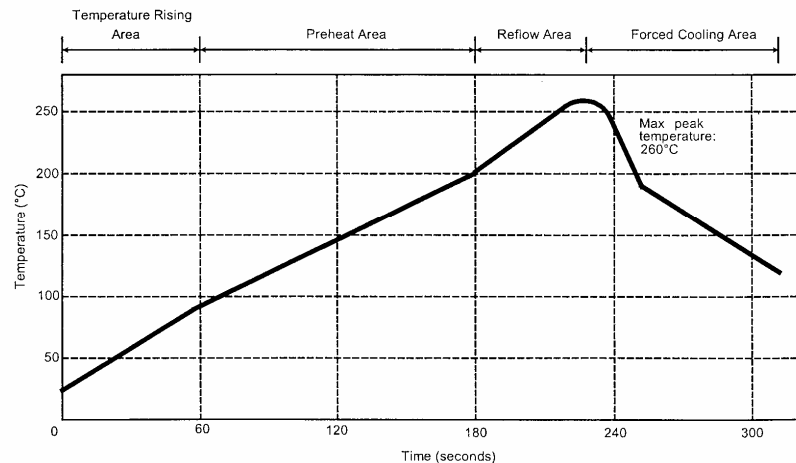
SMA SWITCH EDGE CARD SMT RIGHT TYPE**PACKAGING IN REEL 110****R124.422.001**

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SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 microm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .
5. Verification of solder joints and position of the component by visual inspection.

NOTE : The receptacle and the plug must not be mated before completion of this procedure

TEMPERATURE PROFILE

Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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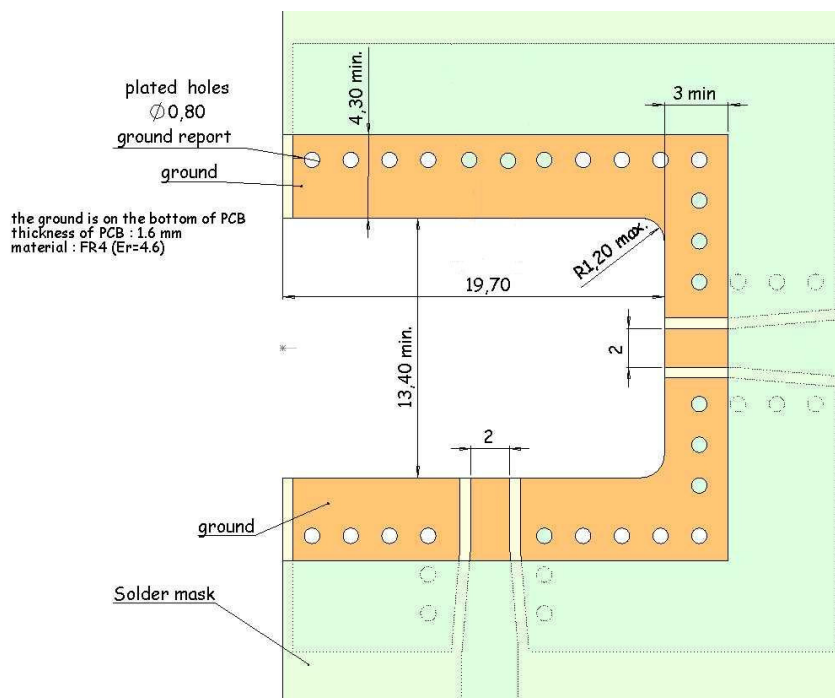
SMA SWITCH EDGE CARD SMT RIGHT TYPE

R124.422.001

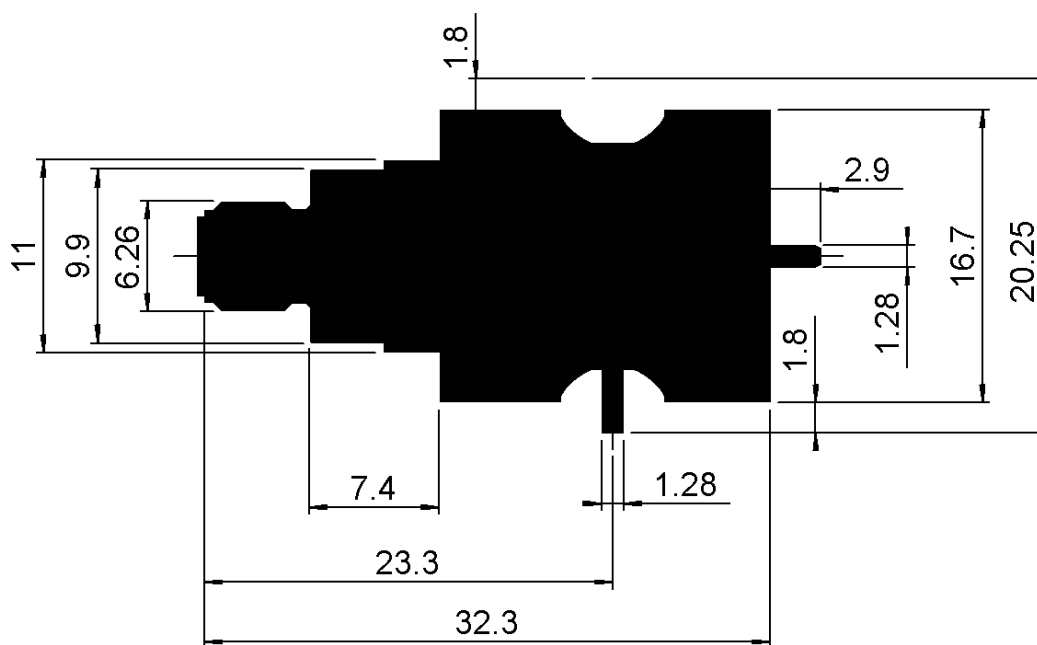
PACKAGING IN REEL 110

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PCB for SMA switch



Shadow of SMA switch for video camera



Issue : 1030 A

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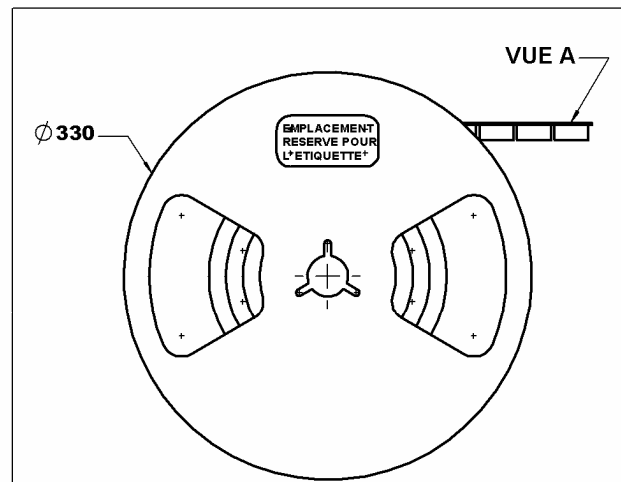


SMA SWITCH EDGE CARD SMT RIGHT TYPE

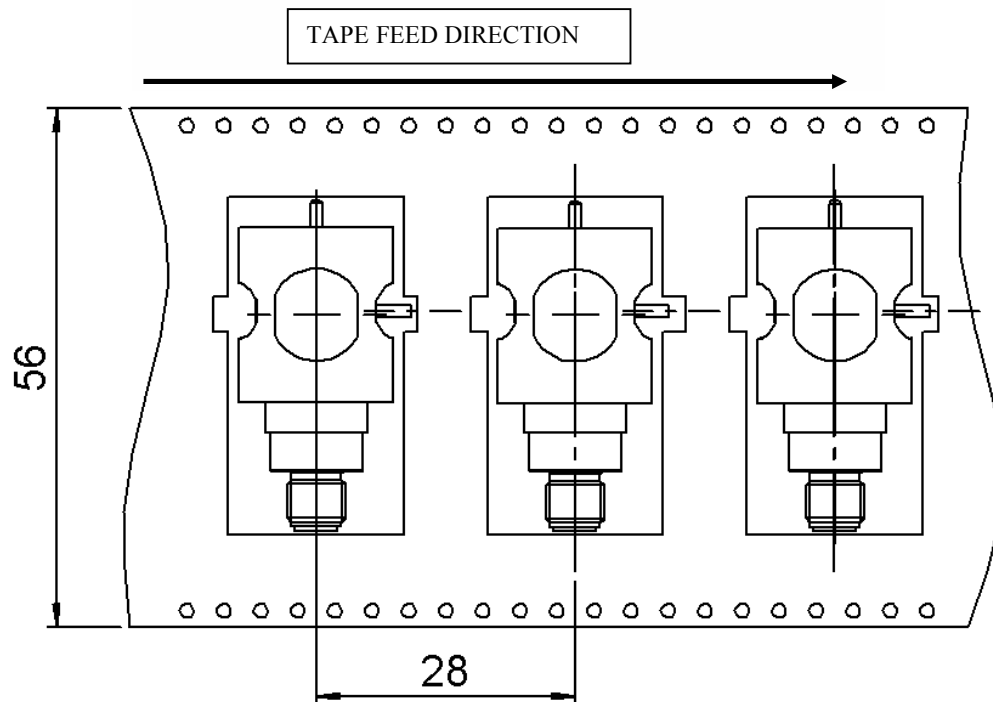
PACKAGING IN REEL 110

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**VUE A**

Issue : 1030 A

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